

Product Advisory (PA)

Subject: Change of the standard interior label of Renesas Electronics

Publication Date: December 1, 2022

Effective Date: Refer to Appendix A to D

Revision Description:

Initial Release

Description of Change:

Renesas Electronics will update and streamline the standard interior labels in shipments for all products in conjunction with our systems integration plan.

Kindly refer to Appendix A to D for comparison on the current and new standard labels.

Materials related to 2D barcode specifications is available upon request.

Affected Product List:

All products, including legacy Intersil, IDT, Dialog and Renesas except custom-labeled products.

Reason for Change:

To integrate company-wide standard labels through the integration of SCM systems, including logistic systems.

Impact on Fit, Form, Function, Quality & Reliability:

This change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Qualification Status: Not applicable

Sample Availability Date: Not applicable

Device Material Declaration: Not applicable

Questions or requests pertaining to this change notice, including additional data, must be sent to Renesas within 30 days of the publication date.

APPENDIX A: LEGACY INTERSIL PRODUCTS

Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign

ABC0001Z	ABC0002A	ABC0002B
2234	2235	2235
2000	1000	1000

D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ◆◆ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

EXP.D 2024/08/30

Seal Date 2022/09/01

Halogen Free

T: 260

RoHS MSL:3

Exempt REACH

MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

2022/09/02

Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

100mm

ABC0001Z	ABC0002A	ABC0002B
2234	2235	2235
2000	1000	1000

D/N RAA462111GBG

SPN RAA462111GBG#ACO AC0YE0100

CPN2 ABC-CORPORATION-02
CPN ABC-CORPORATION-01

PID 223510100A-001 SIZE =12

QTY 4000 PARTIAL ◆◆ SQTY 2

MG LOT 2234ABC0001Z SC: AB

S.LOT YZWF00AA01 MIXED ★

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Halogen Free

T: 260

RoHS MSL:3

Exempt REACH

MC: JPTWTW
ASSEMBLED IN TAIWAN
FROM WAFERS OF JAPAN

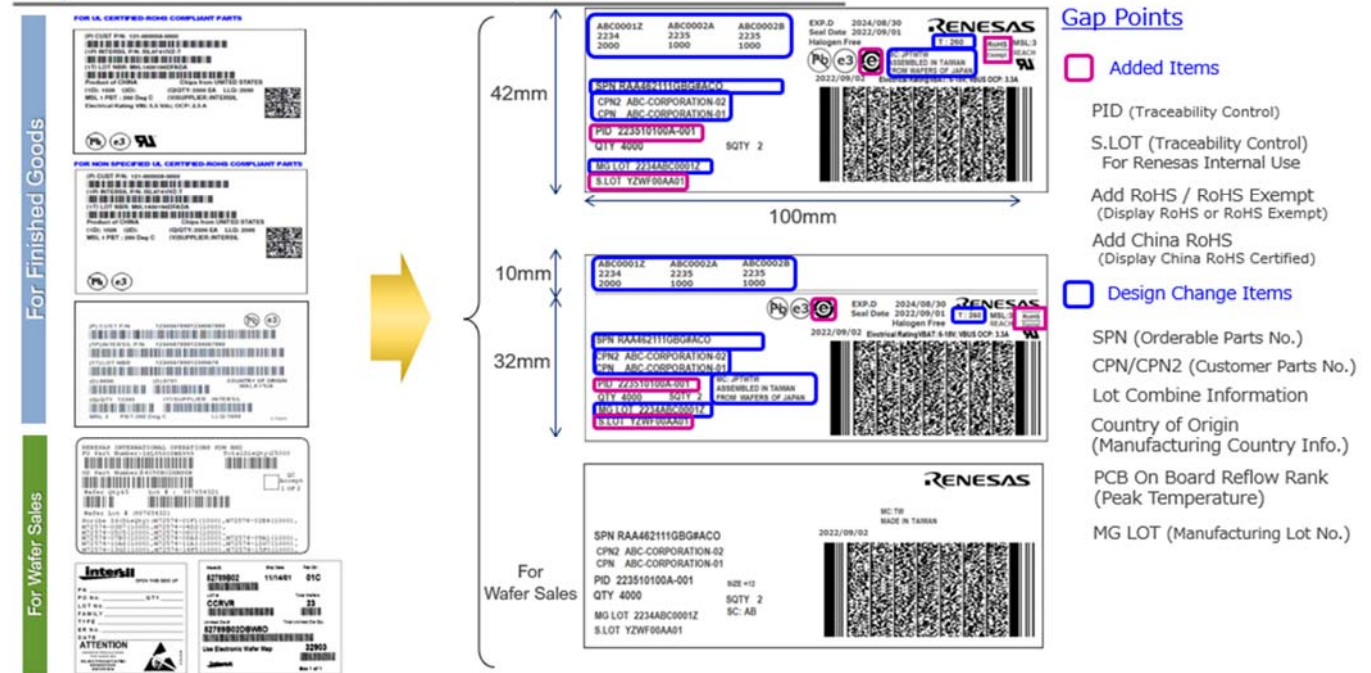
2022/09/02

Electrical Rating VBAT: 6-18V; VBUS OCP: 3.3A

42 mm

Comparison before and after change for legacy INTERSIL products

Gap Points Current and New / Ex-ISL



For additional information regarding this notice, please contact your regional change coordinator (below)

Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM
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APPENDIX B: LEGACY IDT PRODUCTS

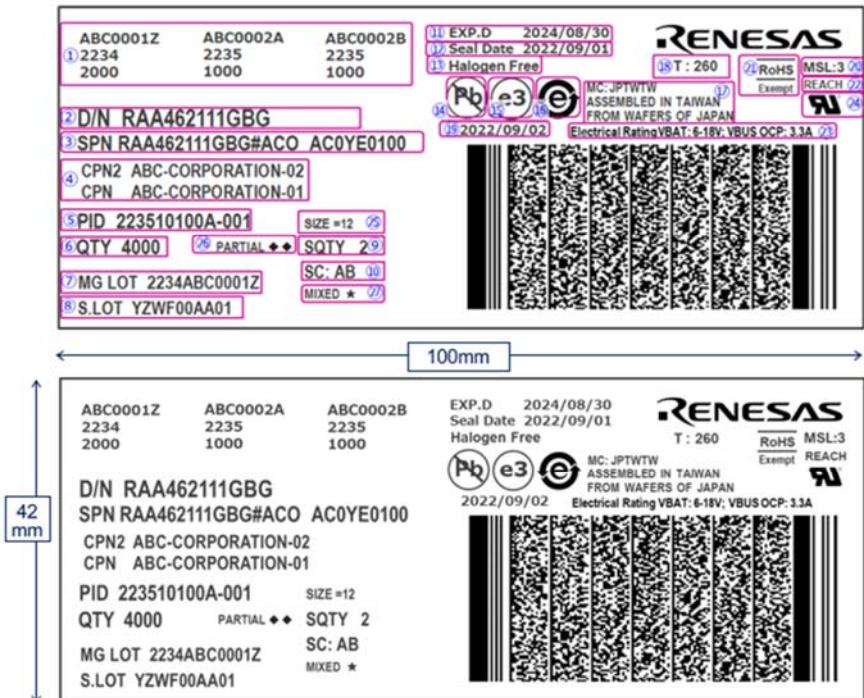
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

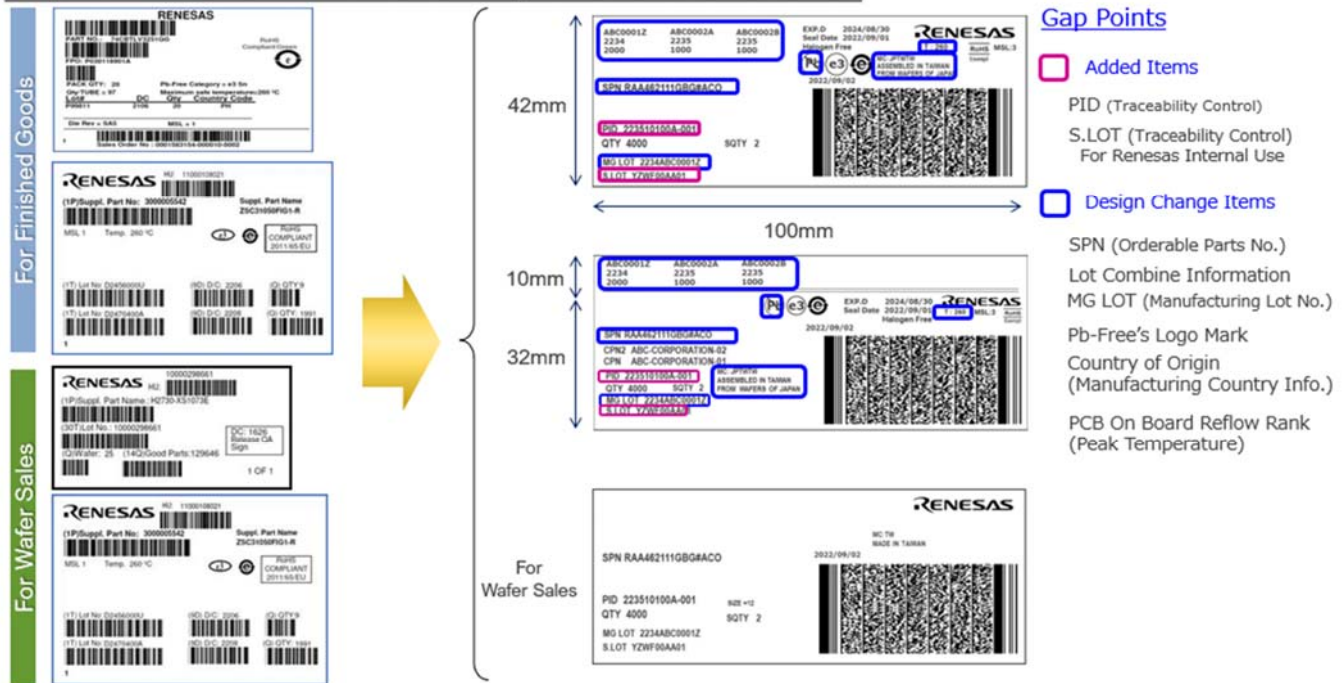
Table 3 : Label Display Item

Label Display Item
① Lot Combine Information
② D/N (Device Name)
③ SPN (SAP Parts Name)
④ CPN / CPN2 (Customer Parts No.)
⑤ PID (Pack ID)
⑥ QTY
⑦ MG LOT (Manufacturing Lot No.)
⑧ S.Lot (Shipping Batch Lot)
⑨ SQTY (Wafers Q'ty)
⑩ OSAT Code
⑪ Expiry Date
⑫ Seal Date
⑬ Halogen Free
⑭ Pb-Free Logo Mark
⑮ Pb-Free with Detail Rank Information
⑯ China RoHS (Logo Mark or "Blank")
⑰ Country of Origin
⑱ PCB On Board Reflow Rank (Peak Temp)
⑲ Labeling Date
⑳ Condition after opening (MSL Rank)
㉑ RoHS Exempt (RoHS or RoHS Exempt)
㉒ REACH Certified (REACH or "Blank")
㉓ UL Certified
㉔ UL Rank
㉕ Wafer Size
㉖ Partial Lot Sign
㉗ Mix Lot Sign



Comparison before and after change for legacy IDT products

Gap Points Current and New / Ex-IDT



For additional information regarding this notice, please contact Idt-pcn@lm.renesas.com.

APPENDIX C: LEGACY DIALOG PRODUCTS

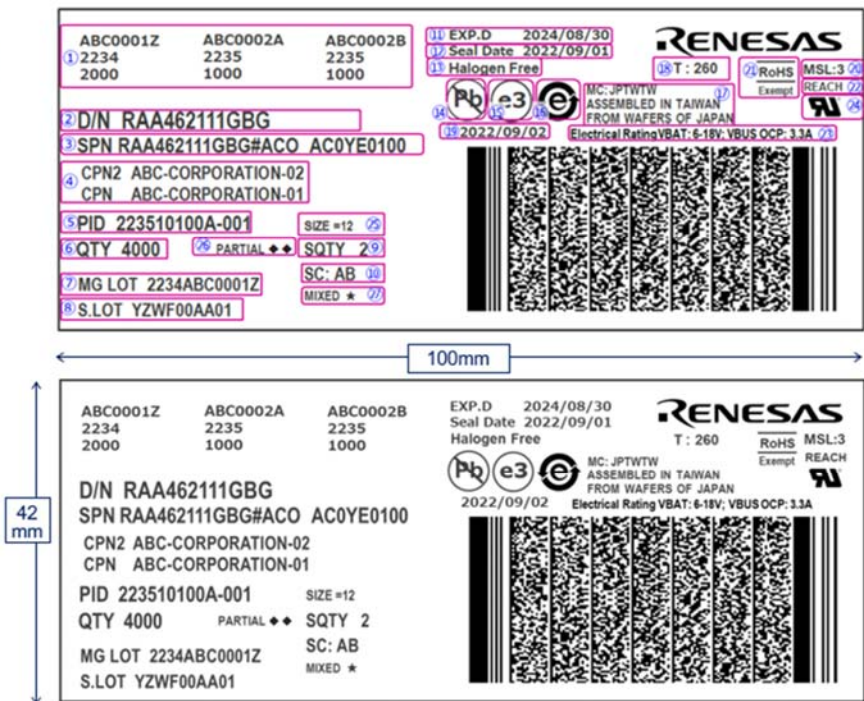
Effective Date: August 1, 2023

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item	
①	Lot Combine Information
②	D/N (Device Name)
③	SPN (SAP Parts Name)
④	CPN / CPN2 (Customer Parts No.)
⑤	PID (Pack ID)
⑥	QTY
⑦	MG LOT (Manufacturing Lot No.)
⑧	S.Lot (Shipping Batch Lot)
⑨	SQTY (Wafers Q'ty)
⑩	OSAT Code
⑪	Expiry Date
⑫	Seal Date
⑬	Halogen Free
⑭	Pb-Free Logo Mark
⑮	Pb-Free with Detail Rank Information
⑯	China RoHS (Logo Mark or "Blank")
⑰	Country of Origin
⑱	PCB On Board Reflow Rank (Peak Temp)
⑲	Labeling Date
⑳	Condition after opening (MSL Rank)
㉑	RoHS Exempt (RoHS or RoHS Exempt)
㉒	REACH Certified (REACH or "Blank")
㉓	UL Certified
㉔	UL Rank
㉕	Wafer Size
㉖	Partial Lot Sign
㉗	Mix Lot Sign



Comparison before and after change for legacy DIALOG products

Gap Points Current and New / Ex-DLG

For Finished Goods

42mm

10mm

32mm

For Finished Goods

For Wafer Sales

Gap Points

Added Items

- PID (Traceability Control)
- EXP. Date (Traceability Control)
- For Renesas Internal Use
- S.LOT (Traceability Control)
- For Renesas Internal Use

Design Change Items

- Renesas Logo Mark
- SPN (Orderable Parts No.)
- CPN/CPN2 (Customer Parts No.)
- MG LOT (Manufacturing Lot No.)
- Lot Combine Information
- Country of Origin (Manufacturing Country Info.)
- PCB On Board Reflow Rank (Peak Temperature)
- SC (Test Supplier Code)

For additional information regarding this notice, please contact your Renesas sales representative.

APPENDIX D: LEGACY RENESAS PRODUCTS

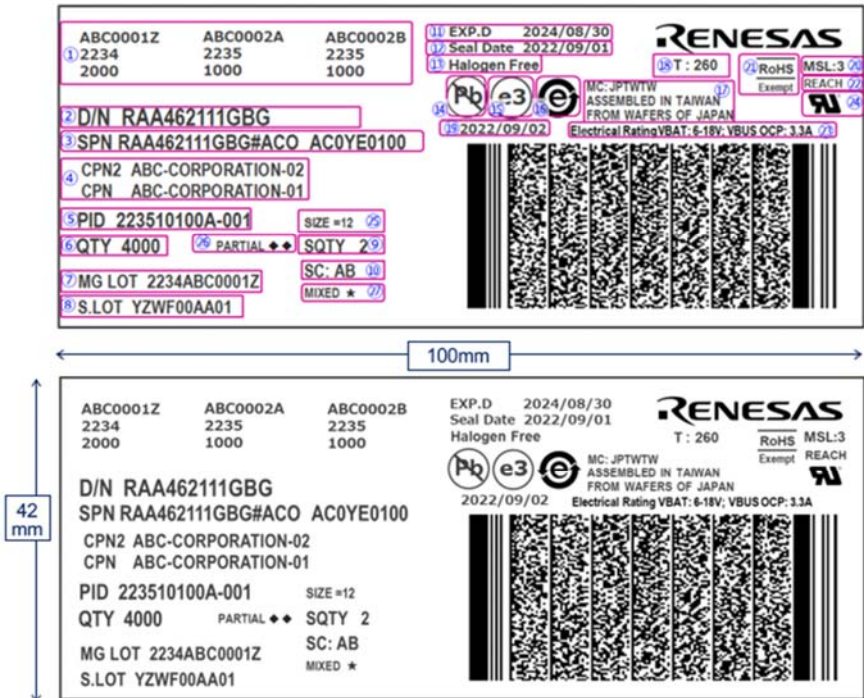
Effective Date: April 1, 2024

Product Identification:

The new standard label after the change is as follows.

Table 3 : Label Display Item

Label Display Item	
①	Lot Combine Information
②	D/N (Device Name)
③	SPN (SAP Parts Name)
④	CPN / CPN2 (Customer Parts No.)
⑤	PID (Pack ID)
⑥	QTY
⑦	MG LOT (Manufacturing Lot No.)
⑧	S.Lot (Shipping Batch Lot)
⑨	SQTY (Wafers Q'ty)
⑩	OSAT Code
⑪	Expiry Date
⑫	Seal Date
⑬	Halogen Free
⑭	Pb-Free Logo Mark
⑮	Pb-Free with Detail Rank Information
⑯	China RoHS (Logo Mark or "Blank")
⑰	Country of Origin
⑱	PCB On Board Reflow Rank (Peak Temp)
⑲	Labeling Date
⑳	Condition after opening (MSL Rank)
㉑	RoHS Exempt (RoHS or RoHS Exempt)
㉒	REACH Certified (REACH or "Blank")
㉓	UL Certified
㉔	UL Rank
㉕	Wafer Size
㉖	Partial Lot Sign
㉗	Mix Lot Sign



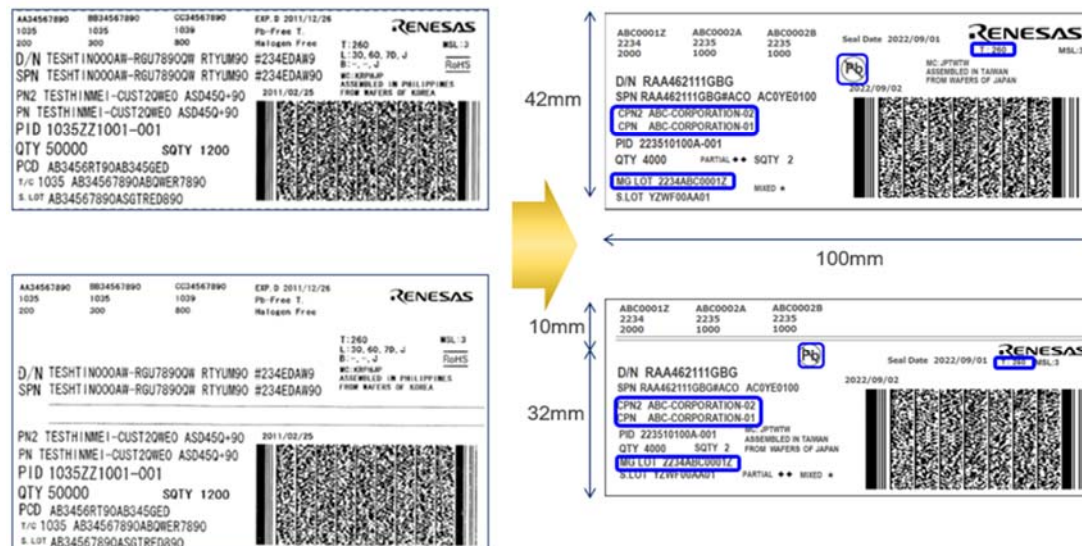
Comparison before and after change for legacy RENESAS products

Gap Points Current and New / Renesas Japan (REL)

Gap Points

☐ Design Change Items

- Pb-Free's Logo Mark
- PCB On Board Reflow Rank (Peak Temperature)
- Customer Parts No. (Display Name Change)
PN/PN2 => CPN/CPN2
- MG LOT (Display Name Change)
T/C => MG LOT
- PCN (Deleted Item)



For additional information regarding this notice, please contact your Renesas sales representative.